

ELECTROCHEMICALLY POLISHING  
CONDUCTIVE FILMS ON SEMICONDUCTOR WAFERS

Abstract of the Disclosure

An electropolish process may remove a conductive film from a semiconductor wafer. An electropolish apparatus having a pad over a platen may make surface-to-surface

5 electrical contact with the conductive film of the wafer across the entire surface of the pad and the conductive film on the wafer. An electric field may be applied through openings in the pad and electrodes which receive potential by feedthroughs that extend through the platen to

10 those electrodes. The electrodes in the feedthroughs may be electrically isolated from the pad and the platen. As a result, more uniform application of electrical potential across the surface to be polished may be achieved in some embodiments.